



## **SPECIFICATION**

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL10C050CB8NCNC
- Description : CAP, 5pF, 50V, ±0.25pF, C0G, 0603

A. Samsung Part Number

			<u>CL</u> ①	<u>10</u> ②	<u>C</u> 3	<u>050</u> ④	<u>C</u> (5)	<u>B</u> 6	<u>8</u> 7	<u>N</u> 8	<u>C</u> (9)	<u>N</u> 10	<u>C</u> 10	
1	Series	Samsung N	/lulti-la	yer Ce	erami	c Capa	acito	r						
2	Size	0603 (i	nch co	de)		L:	1.6	± 0.1		mm		W:	0.8 ± 0.1	mm
3	Dielectric	C0G					8	Inne	r ele	ctroc	le		Ni	
4	Capacitance	<b>5</b> pl	F					Term	nina	tion			Cu	
5	Capacitance	<b>±0.25</b> pl	F					Plati	ng			:	Sn 100%	(Pb Free)
	tolerance						9	Prod	uct				High-Q	
6	Rated Voltage	50 V	,				10	Spec	ial				Reserved for	future use
$\bigcirc$	Thickness	0.8 ±	0.1	mm			1	Pack	agiı	ng			Cardboard T	ype, 7" reel

## B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	1₩±10% 0.5~5Vrms						
Q	500 min							
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance	No abnormal exterior appearance	Microscope (×10)						
Withstanding	No dielectric breakdown or	300% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	C0G							
Characterisitcs	(From -55 $^\circ\!\!\mathbb{C}$ to 125 $^\circ\!\!\mathbb{C}$ , Capacitance change shoud be within ±30PPM/ $^\circ\!\!\mathbb{C}$ )							
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change :	Bending to the limit (1mm)						
	within $\pm 5\%$ or $\pm 0.5$ pF whichever is larger	with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120℃ for 10~30sec.)						
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.						
Soldering heat	within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger							
Tan δ, IR : initial spec.								

	Performance	Test condition					
Vibration Test	Capacitance change :	Amplitude : 1.5mm					
	within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)					
	Tan δ, IR : initial spec.	2hours $\times$ 3 direction (x, y, z)					
Moisture	Capacitance change :	With rated voltage					
Resistance	within $\pm 7.5\%$ or $\pm 0.75pF$ whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs					
	Q : 116.67 min						
	IR : 500Mohm or 25Mohm · μF						
	Whichever is Smaller						
High Temperature	Capacitance change :	With 200% of the rated voltage					
Resistance	within $\pm 3\%$ or $\pm 0.3$ pF whichever is larger	Max. operating temperature					
	Q : 250 min	1000+48/-0hrs					
	IR : 1000Mohm or 50Mohm · μF						
	Whichever is Smaller						
Temperature	Capacitance change :	1 cycle condition					
Cycling	within $\pm 2.5\%$ or $\pm 0.25pF$ whichever is larger	Min. operating temperature $\rightarrow$ 25 °C					
	Tan δ, IR : initial spec.	$\rightarrow$ Max. operating temperature $\rightarrow$ 25 °C					
		5 cycle test					

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max )

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.